

CLAIMS

Having thus described our invention in detail, what we claim is new, and desire to secure by the Letters Patent is:

 $\begin{array}{c} 2\\3\\4\\5\\7\end{array}$

1

8

9

10

11

12

13

14

15

16

17

18

19

20

2122

23

1. A precursor source mixture comprising at least one precursor compound which is dissolved, emulsified or suspended in an inert liquid, said at least one precursor compound having the formula:

 $MR_x^1R_v^2A_z$

where M is an element selected from the group consisting of Li, Na, K, Rb, Cs, Fr, Be, Mg, Ti, Zr, Hf, Sc, Y, La, V, Nb, Ta, Cr\ Mo, W, Mn, Re, Fe, Ru, Os, Co, Rh, Ir, Ni, Pd, Pt, Cu, Ag, Au, Zn, Cd, Hg, B, Al, Ga, In, Tl, Si, Ge, Sn, Pb, As, P, Sb and Bi; R1 and R2 are the same or different ligands selected from the group consisting of hydride, alkyl, alkenyl, cycloalkenyl, aryl, alkyne, carbonyl, amido, imido, hydrazido, phosphido, nitrosyl, nitryl, nitrate, nitrile, halide, azide, alkoxy, siloxy, silyl, and halogenated, sulfonated or silyated derivatives thereof; A is an optional coordinatively bound or associated ligand selected from the group consisting of phosphines, phosphites, amines, arsines, stibenes, ethers, sulfides, nitriles, isonitriles, alkenes, hydrazine, pyridines, nitrogen heterodycles, macrocycles, schiff bases, cycloalkenes, alcohols, phosphine oxides, alkylidenes, nitrites, alkynes, and water; $x \ge 1$; x+y =the valence of element M; and z is ≥ 0 .

Sub 2 3

gswagoz "okedoo

2. The precursor source mixture of Claim 1 wherein said inert liquid is is an aliphatic hydrocarbon, aromatic hydrocarbon, alcohol, ether, aldehyde, ketone, acid, phenol, ester, amine, alkylnitrile, halogenated

hydrocarbon, silvated hydrocarbon, thioether, amine, cyanate, isocyanate, thiocyanate, silicone oil, nitroalkyl, alkylnitrate, or mixtures thereof.

SO

1

6

7

8

9 10

11

1213

14

7

8

9

1011

12

3. The precursor source mixture of Claim 1 wherein M is Li, Na, K, Rb, Cs, Fr, Be, Mg, Ti, Zr, Hf, Sc, Y, La, V, Nb, Ta, Cr, Mo, W, Mn, Re, Fe, Ru, Os, Co, Rh, Ir, Ni, Pd, Pt, Cu, Ag, Au, Zn, Cd, Hg, B, Al, Ga, In, Tl, Si, Ge, Sn, Pb, As, P, Sb or Bi; R¹ is a hydride; R² is a hydride, alkyl, alkenyl, cycloalkenyl, aryl, alkyne, carbonyl, amido, imido, hydrazido, phosphido, nitrosyl, nitryl, nitrate, nitrile, halide, azide, alkoxy, siloxy, silyl, or halogenated, sulfonated or silyated derivatives thereof; and A is a phosphine, phosphite, aryl, amine, arsine, stibene, ether, sulfide, nitrile, isonitrile, alkene, alkyne, hydrazine, pyridine, nitrogen heterocycle, macrocycle, schiff base, cycloalkene, alcohol, phosphine oxide, alkylidene, nitrite or water.

4. The precursor source mixture of Claim 1 wherein M is Li, Na, K, Rb, Cs, Fr, Be, Ti, Zr, Hf, V, Nb, Ta, Cr, Mo, W, Mn, Re, Fe, Ru, Os, Co, Rh, Ir, Ni, Pd, Cu, Ag, Au, Zn, Cd, Hg, B, Al, Ga, In, Tl, Si, Ge, Sn, Pb, As, Sb or Bi; R^1 is a C_1 - C_8 alkyl, or C_4 - C_{12} cycloalkyl; R^2 is a hydride, alkyl, alkenyl, cycloalkenyl, aryl, alkyne, carbonyl, amido, imido, hydrazido, phosphido, nitrosyl, nitryl, nitrate, nitrile, halide, azide, alkoxy, siloxy, silyl, or halogenated, sulfonated or silyated derivatives thereof; and A is a phosphine, phosphite, aryl, amine, arsine, stibene, ether, sulfide, nitrile, isonitrile, alkene, alkyne, hydrazine, pyridine, nitrogen heterocycle,

Cl

 macrocycle, schiff base, cycloalkene, alcohol, phosphine oxide, alkylidene, nitrite, or water.

5. The precursor source mixture of Claim 1 wherein M is Li, Na, K, Rb, Cs, Fr, Be, Ti, Zr, Hf, V, Nb, Ta, Cr, Mo, W, Mn, Re, Fe, Ru, Os, Co, Rh, Ir, Ni, Pd, Cu, Ag, Au, Zn, Cd, Hg, B, Al, Ga, In, Tl, Si, Ge, Sn, Pb, As, Sb or Bi; R¹ is a C₂-C₂ alkenyl, C₄-C₁₂ cycloalkenyl or C₅-C₁ଃ aryl; R² is a hydride, alkyl, alkenyl, cycloalkenyl, aryl, alkyne, carbonyl, amido, imido, hydrazido, phosphido, nitrosyl, nitryl, nitrate, nitrile, halide, azide, alkoxy, siloxy, silyl, and/or halogenated, sulfonated or silyated derivatives thereof; and A is a phosphine, phosphite, aryl, amine, arsine, stibene, ether, sulfide, nitrile, isonitrile, alkene, alkyne, hydrazine, pyridine, nitrogen heterocycle, macrocycle, schiff base, cycloalkene, alcohol, phosphine oxide, alkylidene, nitrite, or water.

6. The precursor source mixture of Claim 1 wherein M is Li, Na, K, Rb, Cs, Fr, Be, Ti, Zr, Hf, V, Nb, Ta, Cr, Mo, W, Mn, Re, Fe, Ru, Os, Co, Rh, Ir, Ni, Pd, Cu, Ag, Au, Zn, Cd, Hg, B, Al, Ga, In, Tl, Si, Ge, Sn, Pb, As, Sb or Bi; R¹ is a carbonyl; R² is a hydride, alkyl, alkenyl, cycloalkenyl, aryl, alkyne, carbonyl, amido, imido, hydrazido, phosphido, nitrosyl, nitryl, nitrate, nitrile, halide, azide, alkoxy, siloxy, silyl, and/or halogenated, sulfonated or silyated derivatives thereof; and A is a phosphine, phosphite, aryl, amine, arsine, stibene, ether, silfide, nitrile, isonitrile, alkene, alkyne, hydrazine, pyridine, nitrogen heterocycle, macrocycle, schiff base, cycloalkene, alcohol, phosphine oxide, alkylidene, nitrite, or water.

7. The precursor source mixture of Claim 1 wherein M is Li, Na, K, Rb, Cs, Fr, Be, Ti, Zr, Hf, V, Nb, Ta, Cr, Mo, W, Mn, Re, Fe, Ru, Os, Co, Rh, Ir, Ni, Pd, Cu, Ag, Au, Zn, Cd, Hg, B, Al, Ga, In, Tl, Si, Ge, Sn, Pb, As, Sb or Bi; R¹ is an alkoxy or siloxy; R² is a hydride, alkyl, alkenyl, cycloalkenyl, aryl, alkyne, carbonyl; amido, imido, hydrazido, phosphido, nitrosyl, nitryl, nitrate, nitrile, halide, azide, alkoxy, siloxy, silyl, and/or halogenated, sulfonated or silyated derivatives thereof; and A is a phosphine, phosphite, aryl, amine, arsine, stibene, ether, sulfide, nitrile, isonitrile, alkene, alkyne, hydrazine, pyridine, nitrogen heterocycle, macrocycle, schiff base, cycloalkene, alcohol, phosphine oxide, alkylidene, nitrite, or water.

8. The precursor source mixture of Claim 1 wherein M is Li, Na, K, Rb, Cs, Fr. Be, Ti, Zr, Hf, V, Nb, Ta, Cr, Mo, W, Mn, Re, Fe, Ru, Os, Co, Rh, Ir, Ni, Pd, Cu, Ag, Au, Zn, Cd, Hg, B, Al, Ga, In, Tl, Si, Ge, Sn, Pb, As, Sb or Bi; R¹ is an amide; R² is a hydride, alkyl, alkenyl, cycloalkenyl, aryl, alkyne, carbonyl, amido, imido, hydrazido, phosphido, nitrosyl, nitryl, nitrate, nitrile, halide, azide, alkoxy, siloxy, silyl, and/or halogenated and sulfonated or silyated derivatives thereof; and A is a phosphine, phosphite, aryl, amine, arsine, stibene, ether, sulfide, nitrile, isonitrile, alkene, alkyne, hydrazine, pyridine, nitrogen heterocycle, macrocycle, schiff base, cycloalkene, alcohol, phosphine oxide, alkylidene, hitrite, or water.

2

3

7 8

9

10

11

12

13 14

15

16 17

1

2

3

4

5

6

7

8

9

10

11

1213

9. The precursor source mixture of Claim 1 wherein the precursor compound has the formula $MR_{x}^{1}(PR_{3}^{2})A_{z}$ where M/is Ti, Zr, Hf, V, Nb, Ta, Cr, Mo, W, Mn, Re, Fe, Ru, Os, Co, Rh, Ir, Ni, Pd, Pt, Cu, Ag or Au, R1 and R2 is a ligand selected from the group consisting of hydride, alkyl, alkenyl, cycloalkenyl, aryl, alkyne, carbonyl, amido, imido, hydrazido, phosphido, nitrosyl, nitryl, nitrate, nitrile, halide, azide, alkoxy, siloxy,/silyl, and/or halogenated, sulfonated or silvated derivatives thereof; A is an optional coordinatively bound ligand selected from the group consisting of phosphines, phosphites, aryls, amines, arsines, stibenes, ethers, sulfides, nitriles, isonitriles, alkenes, alkynes, hydrazine, pyridines, nitrogen heterocycles, macrocycles, schiff bases, cycloalkenes, alcohols, phosphine oxides, alkylidenes, nitrites and water; $x \ge 1$; $y \ge 0$; $z \text{ is } \ge 0$; and x+y = thevalence of M.

10. The precursor source mixture of Claim 1 wherein M is Li, Na, K, Rb, Cs, Fr, Be, Mg, Sc, Y, La, Ce, Pr, Nd, Sm, Eu, Gd, Tb, Dy, Ho, Er, Tm, Yb, Lu, Th, Pa, U Ti, Zr, Hf, V, Nb, Ta, Cr, Mo, W, Mn, Re, Fe, Ru, Os, Co, Rh, Ir, Ni, Pd, Pt, Cu, Ag, Au, Zn, Cd, Hg, B, Al, Ga, In, Tl, Si, Ge, Sn, Pb, As, Sb or Bi; R¹ is a nitrate; R² is a hydride, alkyl, alkenyl, cycloalkenyl, aryl, alkyne, carbonyl, amido, imido, hydrazido, phosphido, nitrosyl, nitryl, nitrate, nitrile, halide, azide, alkoxy, siloxy, silyl, or halogenated, sulfonated or silyated derivatives thereof; and A is a phosphine, phosphite, aryl, amine, arsine, stibene, ether, sulfide, nitrile, isonitrile, alkene, alkyne, hydrazine, pyridine, nitrogen heterocycle,

2

3 4

5

6

7

8 9

10

11

12

13

14

15

1

2

3

5

6

7 8

9

10

11 12

13

macrocycle, schiff base, cycloalkene, alcohol, phosphine oxide, alkylidene, nitrite, or water.

> The precursor source mixture of Claim 1 wherein M is 11. Li, Na, K, Rb, Cs, Fr, Be, Mg, Sc, Y, La, Ce, Pr, Nd, Sm, Eu, Gd, Tb, Dy, Ho, Er, Tm, Yb, Lu, Th, Pa, U Ti, Zr, Hf, V, Nb, Ta, Cr, Mo, W, Mn, Re, Fe, Ru, Os/Co, Rh, Ir, Ni, Pd, Pt, Cu, Ag, Au, Zn, Cd, Hg, B, Al, Ga, In, Tl, Si, Ge, Sn, Pb, As, Sb or Bi; R1 is a halide; R2 is a hydride, alkyl, alkenyl, cycloalkenyl, aryl, alkyne, carbonyl, amido, imido, hydrazido, phosphido, nitrosyl, nitryl, nitrate, nitrile, halide, azide, alkoxy, siloxy, silyl, or halogenated, sulfonated or silvated derivatives thereof; and A is a phosphine, phosphite, aryl, amine, arsine, stibene, ether, sulfide, nitrile, isonitrile, alkene, alkyne, hydrazine, pyridine, nitrogen heterocycle, macrocycle, schiff base, cycloalkene, alcohol, phosphine oxide, alkylidene, nitrite or water.

> 12. The precursor source mixture of Claim 1 wherein M Li, Na, K, Rb, Cs, Fr, Be, Mg, Sc, Y, La, Ce, Pr, Nd, Sm, Eu, Gd, Tb, Dy, Ho, Er, Tm, Yb, Lu, Th, Pa, U Ti, Zr, Hf, V, Nb, Ta, Cr, Mo, W, Mn, Re, Fe, Ru, Os, Co, Rh, Ir, Ni, Pd, Pt, Cu, Ag, Au, Zn, Cd, Hg, B, Al, Ga, In, Tl, Si, Ge, Sn, Pb, As, Sb or Bi; R¹ is a silyl; R² is a hydride, alkyl, alkenyl, cycloalkenyl, aryl, alkyne, carbonyl, amido, imido, hydrazido, phosphido, nitrosyl, nitryl, nitrate, nitrile, halide, azide, alkoxy, siloxy, silyl, and/or halogenated, sulfonated or silyated derivatives thereof; and A is a phosphine, phosphite, aryl, amine, arsine, stibene, ether, sulfide, nitrile, isonitrile, alkene, alkyne, hydrazine, pyridine, nitrogen heterocycle,

macrocycles, schiff base, cycloalkene, alcohol, phosphine oxide, alkylidene, nitrite or water.

Pt; R¹ and R² are hydride, alkyl, alkenyl, cycloalkenyl, aryl, alkyne, carbonyl, amido, imido, hydrazido, phosphido, nitrosyl, nitryl, nitrate, nitrile, halide, azide, alkoxy, siloxy, silyl, or halogenated or sulfonated derivatives thereof, and A is a phosphine, phosphite, aryl, amine, arsine, stibene, ether, sulfide, nitrile, isonitrile, alkene, alkyne, hydrazine, pyridine, nitrogen heterocycle, macrocycle, schiff base, cycloalkene, alcohols, phosphine oxides, alkylidene, nitrites or water, with the proviso sthat the compound is not (cyclopentadienyl) Pt(alkyl).

 $\begin{array}{c}
1 \\
2 \\
3
\end{array}$

- 14. The precursor source mixture of Claim 1 wherein said inert liquid vaporizes at a higher temperature than said at least one precursor compound.
- 15. The precursor source mixture of Claim 2 wherein said inert liquid is a C_{5-12} alkane.
- 16. The precursor source mixture of Claim 1 wherein said inert liquid contains an additive of no more than 30% by volume of the inert liquid.
 - 17. The precursor source mixture of Claim 16 wherein said additive is an additional precursor ligand, an additional precursor adduct, or other coordinating compound selected from the group consisting of phosphines, phosphites, aryls, amines, arsines, stibenes, ethers, sulfides,

nitriles, isonitriles, alkenes, pyridines, heterocycles, 6 tetrahvdrofuran, dimethylformamide, marcrocycles, schiff bases, cycloalkenes, alcohols, phosphine oxides and 9 alkynes. 1 18. The precursor source mixture of Claim 16 wherein the additive is selected from the group consisting of methanol, ethanol, isopropanol, neopentanol, trimethylamine, dimethylethylamine, diethylmethylamine, triethylamine, dimethylamine, diethylamine, 6 bistrimethylsilylamine, ammonia, ethylenediamine, 7 propylenediamine, trimethylethylethylenediamine, 8 triphenylphosphine, triethylphosphine, trimethylphosphine, compay/.c**fi**cac 9 allyl, cyclopentadiene, benzene, ethylbenzene, toluene, cyclohexadiene, cyclooctadiene, cycloheptatriene, 10 cyclooctatetraene, mesitylene, tetrahydroguran, 11 12 dimethylformamide, dimethylsulfoxide, butyl acetate, acetic acid, ethylhexanoic acid, methane, ethane, 13 14 pyridine, and PF3. 19. The precursor source mixture of £laim 1 wherein the 1 2 inert liquid is composed of two or/more components 3 selected from the group consisting of aliphatic 4 hydrocarbons, aromatic hydrocarbons, alcohols, ethers, 5 aldehydes, ketones, acids, phénols, esters, amines, 6 alkylnitrile, halgonated hydrocarbons, silvated 7 hydrocarbons, thioethers, amines, cyanates, isocyanates, 8 thiocyanates, silicone øils, nitroalkyl, alkylnitrate, 9 and/or mixtures of one or more of the above and an additive of no more #han 30% by volume of the inert liquid 10 wherein the additive is selected from the group consisting

11

12

of additional precursor ligand, additional precursor

adduct, and other coordinating compound selected from the 1 2 group consisting of phosphines, phosphites, aryls, amines, arsines, stibenes, ethers, sulfides, mitriles, isonitriles, alkenes, pyridines, heterocycles, tetrahydrofuran, dimethylformamide, marcrocycles, schiff bases, cycloalkenes, alcohols, phosphine oxides, and 6 7 alkynes. NO. The precursor source mixture of Claim 19 wherein the 1 additive is selected from the group consisting of methanol, ethanol, isopropanol, neopentanol, trimethylamine, dimethylethylamine, diethylmethylamine, triethylamine, dimethylamine, diethylamine, bistrimethylsilylamine, ammonia, ethylenediamine, Couldoor " chido 6 propylenediamine, trimethylethylethylenediamine, triphenylphosphine, triethylphosphine, trimethylphosphine, 9 allyl, cyclopentadiene, benzene, ethylbenzene, toluene, cyclohexadiene, cycloocbadiene, cycloheptatriene, 10 cyclooctatetraene, mesitylene, tetrahydroguran, 11 dimethylformamide, dimethylsulfoxide, butyl acetate, 12 13 acetic acid, ethylhexanoic acid, methane, ethane, 14 pyridine, and PF3. 21. The precursor source mixture of Claim 1 wherein the 1 inert liquid is composed of C₅-C₁₂ Akane and contains an 2 additive of no more than 30% by volume of the inert liquid 3 wherein the additive is selected from the group consisting 4 of an additional precursor ligand, an additional precursor 5 adduct, or other coordinating compound selected from the 6 group consisting of phosphines, phosphites, aryls, amines, 7

8 9 arsines, stibenes, ethérs, sulfides, nitriles,

isonitriles, alkenes, pyridines, heterocycles,

tetrahydrofuran, dimethylformamide, marcrocycles, schiff bases, cycloalkenes, alcohols, phosphine oxides, and alkynes.



22. The precursor source mixture of Claim 21 wherein the additive is methanol, ethanol, isopropanol, neopentanol, trimethylamine, dimethylethylamine, diethylamine, triethylamine, dimethylamine, diethylamine, bistrimethylsilylamine, ammonia, ethylenediamine, propylenediamine, trimethylethylethylenediamine, triphenylphosphine, triethylphosphine, trimethylphosphine, allyl, cyclopentadiene, benzene, ethylbenzene, toluene, cyclohexadiene, cyclooctadiene, cycloheptatriene, cyclooctatetiaene, mesitylene, tetrahydroguran, dimethylformamide, dimethylsulfoxide, butyl acetate, acetic acid, ethylhexanoic acid, methane, ethane, pyridine, or PF₃.

23. The precursor source mixture of Claim 1 wherein the at least one precursor compound is dimethyl-, diethyl-, or diisobutyl B, Al, Ga, In, As, or Sb hydride;

Me₂AlH(NEtMe₂); tertbutylarsine; (Me₃N)AlH₃; (EtMe₂N)AlH₃; (Et₃N)AlH₃; CpWH₂; Cp₂MoH₂; trimethyl-, triethyl-, triisobutyl-, tri-n-proxyl-, tri-isopropyl-, tri-n-butyl-, trineopentyl-, or ethyldimethyl- B, Al, Ga, In, As or Sb; tetramethyl-, tetraethyl-, tetraphenyl-, or tetra-n-butyl-Si, Ti, Zr, Hf, Ge, Sn, or Pb; dimethyl-, diethyl-, or diisobutyl- B, Al, Ga, In, As or Sb, hydride, chloride, fluoride, bromide, iodide, p, amide, dimethylamide or azide; triethyl-, triisobutyl, tri-n-propyl-, triisopropyl-, tri-n-butyl- or ethyldimethyl- B, Al, Ga, In, As or Sb trimethylamine, diethylmethylamine,

```
dimethylethylamine, or triethylamine; dimethyl- or
15
           diethyl- Zn, Cd, or Hg; (neopentyl) (Cr; Et, Pb (neopentoxy);
16
           Cp.Me, Zr; (MeNC), PtMe; CpIr(C,H4); bisCp-Co, Mo, Fe, Mn,
17
           Ni, Ru, V, Os, Mg or Cr; bisethylbenzene; bisbenzene-Co,
18
           Mo or Cr; triphenyl-Bi, Sb, or As; trivinylboron; trisCp-
19
           Sc, Y, La, Ce, Pr, Nd, Sm, Eu, Gd, Tb, D, Ho, Er, Tm, Yb,
20
           or Lu; tetraCp-Th, Pa, U, Np, Pu, or Am trisallyliridium;
21
           CpCr(CO); Cp,ZrMe,; CpCuPEt,; CpIn; CpIr(cyclooctadiene);
22
           CpPd(ally1) CpGaMe2; CpGaEt2; (cyclohexadiene) FeCO3;
23
           (cyclooctate\frame) FeCO; ethylferrocene; CpMn(CO);
24
           (cycloheptatriene) Mo(CO); TlCp; Cp2WH2;
25
           (mesitylene) W(CQ); CpRe(CO); CpRh(CO); Ir(allyl);
26
           Pt(allyl); CpIr(cyclooctanedione);
27
           [Ir (OMe) (cyclooctanedione)];
28
           Ru(cyclooctanedione)(ally\mathbf{A})<sub>2</sub>; Ru<sub>3</sub>CO<sub>12</sub>; Fe(CO)<sub>5</sub>; Co<sub>2</sub>(CO)<sub>8</sub>;
29
           Ru(CO), (1,3-cyclohexadiene); Os_3CO_{12}; Cr(CO)_6; CpCo(CO)_2;
30
           Mn_2(CO)_{10}; CpMn(CO)<sub>3</sub>; (c\closevelontriene)Mo(CO)<sub>3</sub>; Mo(CO)<sub>6</sub>;
31
           Ni (CO)<sub>4</sub>; Re<sub>2</sub> (CO)<sub>10</sub>; CpRe (^{\circ}CO)<sub>3</sub>; CpRh (CO)<sub>2</sub>; Ru<sub>3</sub> (CO)<sub>12</sub>; W (CO)<sub>6</sub>;
32
           CpV(CO)_4; CF_3Co(CO)_4; Pt(CO)_2 (cyclooctanedione);
33
           Ir(CO)_2(cyclooctanedione); (CO)_4Fe[P(OCH_3)_3];
34
           (CO)_4 Fe[N(CH_3)_3]; CONO(CO)_3; Autoxy, OCH(CF_3)_2, OCMe_2(CF_3),
35
           OCMe(CF_3)_2, OSi(CH_3)_3, OC(CH_3)_3 OC(SiMe_3)_3, or OC(CF_3)_3 Li,
36
           Na, K, Rb, Cs, Fr, Cu, Ag, Au, Hg, or Tl; tetra-methoxy,
37
           tetra-ethoxy, tetra-isopropoxy, tetra-butoxy, tetra-tert-
38
           butoxy, tetra-isobutoxy, tetra-OC\Lambda(CF<sub>3</sub>)<sub>2</sub>, tetra-OCMe<sub>2</sub>(CF<sub>3</sub>),
39
           tetra-OCMe(CF<sub>3</sub>)<sub>2</sub>, tetra-OC(CH<sub>3</sub>)<sub>3</sub>, tetra-OC(SiMe<sub>3</sub>)<sub>3</sub>, tetra-
40
           OC(CF_3)_3 or tetra-OSi(CH_3)_3 Si, Ge, Sn \setminus Pb, Ti, Zr, or Hf;
41
           VO(isopropoxy), tri-isopropoxy, tri-sec-butoxy, tri-
42
           n-butoxy, tri-iso-butoxy, tri-methoxy, tri-ethoxy, tri-
43
           OCH(CF_3)_2, tri-OCMe_2(CF_3), tri-OCMe(CF_3)_2, tri-OC(CH_3)_3, tri-OCMe_3(CF_3)_2
44
           OC(SiMe_3)_3, tri-OC(CF_3)_3, or tri-OSi(CH_3)_3, B Al, Ga, In,
45
           P, As, or Sb; Et<sub>3</sub>Pb(isopropoxide); (tertbutoxy)CuPMe<sub>3</sub>;
46
```

```
47
           tetrakis (dimethylamino), tetrakis (diethylamino) Ti, Zr,
               Si, Ge, Sn, or Pb; diethylaminodiethylarsine;
48
           diethylaminoarsine dichloride; bisdimethylaminoarsine
49
50
           chloride; Me, Zn (triethylamine),;
51
           diethylaminodimethylstannane; tris(dimethylamino)
52
           phosphine; tris(dimethylamino) antimony;
           tris(dimethylamino) arsine; tris(dimethylamino) stibine;
53
54
           tris-bis(trimethylsilyl)erbium amide;
           bis (dimethylamino) (trimethylethylethylenediamino)
55
           aluminium; (CO) Fe [N (CH, Li, Na, or K N (SiMe3),
56
           pentadimethylaminotantalum; diethylaminodimethyltin;
57
           hexadimethylaminoditungsten;
58
           trisdimethylamino(trimethylethylenediamino)titanium;
59
60
           CpCu(PEt3); CpCu(triphenylphospine); (tertbutoxy)CuPMe3;
           Pt(PF<sub>3</sub>)<sub>4</sub>; Ni(PF<sub>3</sub>)<sub>4</sub>; Cr(PF<sub>3</sub>)<sub>6</sub>; \( Et<sub>3</sub>P)<sub>3</sub>Mo(CO)<sub>3</sub>; Ir(PF<sub>3</sub>)<sub>4</sub>;
61
           Ti(NO_3)_4; Zr(NO_3)_4; Hf(NO_3)_4; Si(CH_3)_3(NO_3); RuNO(NO_3)_3;
62
           gallium nitrate; Sn(NO_3)_4; Co(NO_3)_3; VO(NO_3)_3; CrO_2(NO_3)_2;
63
64
           TiCl<sub>4</sub>; ZnCl<sub>2</sub>; ZrCl<sub>4</sub>; HfCl<sub>4</sub>; AlCl<sub>3</sub>; SiCl<sub>4</sub>; GaCl<sub>3</sub>; SnCl<sub>4</sub>;
           CoCl; dimethyl, diethyl, or diisobatyl, Al, B, Ge, Si, or
65
           As halide; N(SiMe_3)_2 Li, Na, or K; B(OH_2SiMe_3)_3; \{(Me_3Si)_2N\}_3
66
           B, Al, Ga or In; (Me<sub>3</sub>SiCH<sub>2</sub>)<sub>4</sub> Ti, Zr or HX; or {(Me<sub>3</sub>Si)<sub>2</sub>N}<sub>2</sub>
67
68
           Zn, Cd or Hg, where Cp is cyclopentadien
```

24. A method for chemical vapor deposition or atomic layer deposition comprising: vaporizing the precursor compound in the precursor source mixture of Claim 1, introducing the vaporized precursor into a chemical vapor deposition or atomic layer deposition reactor with optional addition of other co-reactant(s), and depositing a constituent of the vaporized precursor on a substrate to form a film.

1	25.	The	meth	nod	of	${\tt Claim}$	24	wherein	said	film	is	a
2	compo	nent	in	an	ele	ectron	ic (device.				

- 26. The method of Claim 24 wherein said co-reactant(s) is introduced separately from said vaporized precursor.
- 27. The method of Claim 24 comprising vaporizing the precursor in the precursor source mixture, and introducing the vaporized precursor into an atomic layer deposition reactor with separate addition of other co-reactant(s) and inert purge gas and depositing a film on a substrate by sequential introduction of alternating pulses of vaporized precursor(s), purge gas co-reactant(s) and purge gas.
- 28. The method of Claim 24 wherein the co-reactant is a reducing agent, an oxidizing agent, a nitriding agent or a silyating agent.
- 29. The method of Claim 28 wherein said reducing agent is selected from the group consisting of hydrogen, forming gas, silane, and combinations thereof.
- 30. The method of Claim 28 wherein said oxidizing agent is selected from the group consisting of oxygen, ozone, water, hydrogen peroxide, nitrous oxide, and combinations thereof.
- 31. The method of Claim 28 wherein said nitriding agent is selected from the group consisting of ammonia, hydrazine, hydrogen azide, tertbutylamine isopropylamine, and combinations thereof.



32. The method of Claim 28 wherein said silvating agent is selected from the group consisting of silane, dislanes, chlorosilanes, silvamines, silazanes, and combinations thereof.

e

33. The method of Claim 24 comprising subjecting said substrate to a sequence of alternating pulses of three or more different gases wherein one of said gases comprises vaporized precursor of said precursor source mixture, another of said gases is a purge gas and another of said gases is a reducing agent.

34. The method of Claim 24 comprising subjecting said substrate to a sequence of alternating pulses of three or more different gases wherein one of said gases comprising said vaporized precursor of said precursor source mixture, another of said gases is a purge gas and another of said gases is an nitriding agent.

35. The method of Claim 24 comprising subjecting said substrate to a sequence of alternating pulses of four or more different gases, wherein one of said gases comprises said vaporized precursor of said precursor source mixture, another of said gases is a purge gas, another of said gases is an oxidizing agent and another of said gases is selected from the group consisting of any vaporized precursor and a vaporized precursor of a precursor source mixture according to Claim 1.

36. The method of Claim 24 comprising subjecting said substrate to a sequence of alternating pulses of four or more different gases, wherein one of said gases comprises

 vaporized precursor of said precursor source mixture, another of said gases is a purge gas, another of said gases is an nitriding agent and another of said gases is selected from the group consisting of any vaporized precursor and a vaporized precursor of a precursor source mixture according to Claim 1.

37. The method of Claim 24 comprising subjecting said substrate to a sequence of alternating pulses of four or more different gases, wherein one of said gases comprises vaporized precursor of said precursor source mixture, another of said gases is a purge gas, another of said gases is a reducing agent and another of said gases is selected from the group consisting of any vaporized precursor and a vaporized precursor of a precursor source mixture according to Claim 1.

38. The method of Claim 24 comprising subjecting said substrate to a sequence of alternating pulses of five or more different gases wherein one of said gases comprises vaporized precursor of said precursor source mixture, another of said gases is a purge gas, another of said gases is a reducing agent and another of said gases is selected from the group consisting of any Si containing vaporized precursor and a Si containing vaporized precursor of a precursor source mixture according to Claim 1.

39. The method of Claim 24 wherein the substrate is selected from the group consisting of semiconductor substrates, dielectrics, metals, organic substrates, glasses, metal oxides, and plastic polymeric substrates,

ı	1
X	2
/\	3
•	2

Si-containing semiconductor substrates, ceramics, silicon on-insulator substrates, Ge substrates, SiGe substrates, GaAs substrates, and mixtures or multilayers thereof.

40. The method of Claim 25 wherein said electronic device is a transistor, capacitor, diode, resistor, switch, light emitting diode, laser, wiring structure, or interconnect structure.

- 41. A method of fabricating a stack or trench capacitor structure composed of a bottom electrode, a dielectric layer, a top electrode layer and an optional dielectric buffer layer over said capacitor which is connected to underlying circuitry via a plug and optional barrier wherein at least one component of the capacitor structure is deposited according to Claim 24.
- 42. The method of Claim 41 wherein the optional dielectric barrier is selected from the group consisting of SiO_2 , SiO_xN_y , Si_3N_4 TiON, AlN, SiN, TiN, Ta_2O_5 , TiO_2 , ZrO_2 , HfO_2 , Al_2O_3 , La_2O_3 , Y_2O_3 , alloys, mixtures or layers thereof, and multicomponent metal oxides.
- 43. The method of Claim 41 wherein the dielectric is a ferroelectric material.
- 44. The method of Claim 41 wherein the plug material is selected from the group consisting of polysilicon, W, Mo, Ti, Cr, Cu, and doped or undoped alloys, mixtures and multilayers thereof.

KY

45. The method of Claim 41 wherein the conductive barrier is selected from the group consisting of TaN, TaSiN, TiAlN, TiSiN, TaSiN, TaWN, TiWN, TaSiN, TaAlN, NbN, ZrN, TaTiN, TiSiN, TiAlN, IrO $_{\rm x}$, Os, OsO $_{\rm x}$, MoSi, TiSi, ReO $_{\rm 2}$, and doped or undoped alloys, mixtures and multilayers thereof.

 $2 \begin{vmatrix} 1 \\ 2 \\ 3 \end{vmatrix}$

3 4

5

46. The method of Claim 41 wherein the bottom electrode is selected from the group consisting of conductive materials, polysilicon, Ni, Pd, Pt, Cu, Ag, Au, Ru, Ir, Rh, OrO_x, TaN, TaSiN, Ta, SrRuO₃, LaSrCoO₃, and doped or undoped alloys, mixtures and multilayers thereof.

14

15

16

1

2

47. The method of Claim 41 wherein the/dielectric material is selected from the group consisting of SiO2, $SiO_{x}N_{y}$, $Si_{3}N_{4}$, $Ta_{2}O_{5}$, TiO_{2} , ZrO_{2} , HfO_{2} , $Al_{2}O_{3}$, $La_{2}O_{3}$, $Y_{2}O_{3}$, multicomponent metal oxides, pervoskite type oxide having the formula ABO, wherein B is at Aeast one acid oxide containing a metal selected from the group consisting of Al, Ti, Zr, Hf, V, Nb, Ta, Cr/ Mo, W and Cu, and A is at least one additional cation/having a positive formal charge of from about 1 to about 3, barium strontium titanate, barium strontium zirconate, barium strontium hafnate, lead titanate, yttrium alumnate, lanthanum alumnate, lead zirconium titanate, strontium bismuth tantalate, strontium bismuth niobate, bismuth titanate, lanthanum silicate, yttrium silicate, hafnium silicate, zirconium silicate, rate earth doped silicates and doped or undoped alloys, mixtures and multilayers thereof.

48. The method of Claim 41 wherein the top electrode is selected from the group consisting of polysilicon, Ni, Pd, Pt, Cu, Ag, Au, Ru, Ir, Rh, IrO_x , TaN, TaSiN, Ta, $SrRuO_3$,

4 LaSrCoO₃, and doped or undoped alloys, mixtures and multilayers thereof.

- 49. A method of fabricating a wiring structure composed of etched trenches and vias into a dielectric layer, optional barrier material between dielectric and wiring material, and wiring material wherein at least one component of the wiring structure is deposited according to Claim 24.
 - 50. The method of Claim 49 wherein the dielectric layer is selected from the group consisting of ${\rm SiO_2}$, ${\rm SiO_xN_y}$, ${\rm Si_3N_4}$, phosphosilicate glass, metal oxides, ${\rm Al_2O_3}$ and doped or undoped alloys, mixtures and multilayers thereof.
 - 51. The method of Claim 49 wherein the optional barrier material is selected from the group consisting of WN, TiN, TaN, SiO_2 , SiO_xN_y , Si_3N_4 , phosphosilicate glass, metal oxides, Al_2O_3 , and doped or undoped alloys, mixtures and multilayers thereof.
 - 52. The method of Claim 49 wherein the wiring material is selected from the group consisting of polysilicon, Al, W, Mo, Ti, Cr, Cu and doped or undoped alloys, mixtures and multilayers thereof.
 - 53. A method of fabricating an electronic device composed of a substrate having source and drain regions and a channel region between said source and drain regions, a gate dielectric, aligned to and on top of said channel region, and a gate electrode aligned to and on top of said

5

6 7

8

9

10

11

12

13

14

15

16

1 2

1

2

3

6 gate dielectric wherein at least one component of the 7 electronic device is deposited according to Claim 24.

> 53. A method of Claim 53 wherein the gate dielectric selected from the froup consisting of SiO2, SiON, Si3N4, Ta_2O_5 , TiO_2 , ZrO_2 , HfO_2 , Al_2O_3 , La_2O_3 , \cancel{Y}_2O_3 , multicomponent metal oxides, pervoskite type oxide having the formula ABO, wherein B is at least one acid oxide containing a metal selected from the group consisting of Al, Ti, Zr, Hf, V, Nb, Ta, Cr, Mo, W, and Cu, and A is at least one additional cation having a positive formal charge of from about 1 to about 3, barium strontium titantate, barium strontium zirconate, barium strontium hafnate, lead titanate, yttrium alumnate, lanthanum alumnate, lead zirconium titarate, strontium bismuth tantalate, strontium bismuth niobate, bismuth titanate, lanthanum silicate, yttrium silicate, hafnium silicate, zirconium silicate, rare earth doped silicates and doped or undoped alloys, mixtures and multilayers thereof.

55. The method of Claim 53 wherein gate dielectric is composed of more than one layer.

56. The method of Claim 53 wherein the gate electrode is selected from the group consisting of polysilicon, Al, Ag, Bi, Cd, Fe, Ga, Hf, In, Mn, Nb, Y, Zr, Ni, Pt, Be, Ir, Te, Re, Rh, W, Mo, Cr, Fe, Pd, Au, Rh, Ti, Cr, Cu, and doped or undoped alloys, mixtures and multilayers thereof.

